

Structure	Silicon monolithic Integrated circuit
Product	Clock Generator
Type	BU3056FV
Feature	To generate clocks for BD-player, BD-recorder system Selection of PDB pin enabling Power-Down function

○Absolute Maximum Ratings

Parameter	Symbol	Ratings	Unit
Supply voltage	VDD	-0.3 ~ 4.0	V
Input Voltage	VIN	-0.3 ~ VDD+0.3	V
Storage Temperature range	Tstg	-55 ~ 125	°C
Power dissipation	PD	450 ^{※1}	mW

- ※1 A measure value at mounting on 70mm×70mm×1.6mm glass epoxy substrate.
In the case of exceeding Ta=25°C, 4.5mW should be reduced per 1°C.
- ※ The radiation-resistance design is not carried out.
- ※ Operation is not guaranteed.

○Operating Conditions

Parameter	Symbol	Ratings	Unit
Supply voltage	VDD	3.0 ~ 3.6	V
Input "H" Voltage	VIH	0.8VDD ~ VDD	V
Input "L" Voltage	VIL	0.0 ~ 0.2VDD	V
Operating Temperature	Topr	-20 ~ 85	°C
Output load	CL	15 (MAX)	pF

Status of this document

The Japanese version of this document is the formal specification.

A customer may use this translation version only for a reference to help reading the formal version.

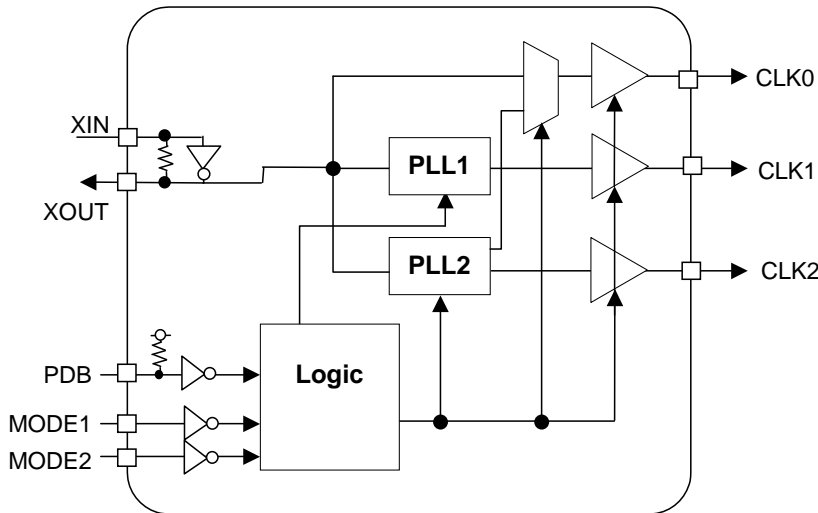
If there are any differences in translation version of this document, formal version takes priority.

○ **Electrical Characteristics**

(VDD=3.3V, Ta=25°C, at No Load ,unless otherwise specified)

Parameter	Symbol	Limit			Unit	Conditions
		Min.	Typ.	Max.		
Pull-up load	Rpu	28	59	90	kΩ	Input PIN pull-up load value
Pull-down load	Rpd	25	53	80	kΩ	Input PIN pull-down load value
Output H voltage	VOH	2.9	—	—	V	IOH= - 4.0mA
Output L voltage	VOL	—	—	0.4	V	IOL=4.0mA
Consumption current1	IDD1	—	16	21	mA	MODE1=L, MODE2=L, Xtal=12.000MHz
Consumption current2	IDD2	—	25	33	mA	MODE1=L, MODE2=H, Xtal=12.000MHz
Consumption current3	IDD3	—	22	29	mA	MODE1=H, MODE2=L, Xtal=24.576MHz
Consumption current4	IDD4	—	13	17	mA	MODE1=H, MODE2=H, Xtal=25.000MHz

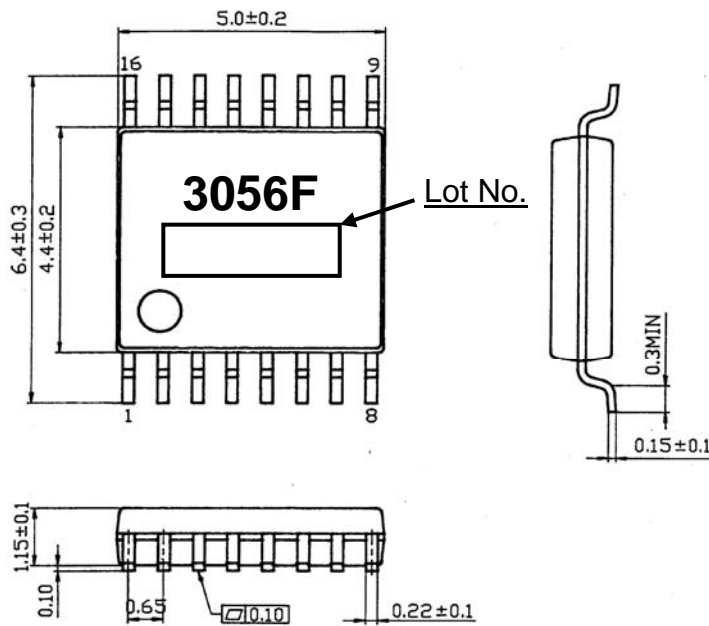
○ **Block Diagram**



○ **Output Frequency**

MODE1	MODE2	PDB	Input Frequency	CLK0	CLK1	CLK2
L	L	L	12.0000MHz	L Output	L Output	L Output
		H	12.0000MHz	12.0000MHz	33.3333MHz	27.0000MHz
L	H	L	12.0000MHz	L Output	L Output	L Output
		H	12.0000MHz	12.0000MHz	60.0000MHz	48.0000MHz
H	L	L	24.5760MHz	L Output	L Output	L Output
		H	24.5760MHz	24.5760MHz	25.0000MHz	48.0000MHz
H	H	L	25.0000MHz	L Output	L Output	L Output
		H	25.0000MHz	25.0000MHz	25.0000MHz	25.0000MHz

○Package Outline, Appearance of Marker



SSOP-B16

(UNIT : mm)

○Pin Function

PIN No.	PIN Name	Function	PIN No.	PIN Name	Function
1	VDD0	Power supply for CLK0 output	9	MODE2	MODE control terminal 2 (CMOS Input)
2	VSS0	GND for CLK0 output	10	MODE1	MODE control terminal 1 (CMOS Input)
3	CLK0	CLK0 output terminal	11	CLK1	CLK1 output terminal
4	AVDD	Analog power supply	12	VSS	Logic GND
5	AVSS	Analog GND	13	VDD	Logic power supply
6	XIN	Crystal input terminal	14	CLK2	CLK2 output terminal
7	XOUT	Crystal output terminal	15	PDB	Power-Down control terminal With pull-up resistor
8	TEST	TEST terminal is normally OPEN With pull-down resistor	16	TEST_B	TEST terminal is normally OPEN With pull-down resistor

●Cautions on use (BU3056FV)

- BU3056FV must be basically mounted on the board. (If it is not circuit board mounting, it can't sometimes get a character fully.)
- Capacitors 0.1uF need to be placed between 1PIN(VDD0) and 2PIN(VSS0), 4PIN(AVDD) and 5PIN(AVSS), 13PIN(VDD) and 12PIN(VSS).
- It is effective as an EMI countermeasure when the capacitor (less than 1Ω) which puts ferrite beads in the starting point of the power supply supplied to the BU3056FV by a circuit board and which makes the power supply-GND space have a requested high frequency as to the bypass is inserted.
- For ICs with more than one power supply, it is possible that rush current may flow instantaneously due to the internal powering sequence and delays. Therefore, give special consideration to power coupling capacitance, power wiring, width of ground wiring, and routing of wiring.

● Cautions on use (common)

(1) Absolute Maximum Ratings

An excess in the absolute maximum ratings, such as supply voltage, temperature range of operating conditions, etc., can break down devices, thus making impossible to identify breaking mode such as a short circuit or an open circuit. If any special mode exceeding the absolute maximum ratings is assumed, consideration should be given to take physical safety measures including the use of fuses, etc.

(2) Operating conditions

These conditions represent a range within which characteristics can be provided approximately as expected. The electrical characteristics are guaranteed under the conditions of each parameter.

(3) Reverse connection of power supply connector

The reverse connection of power supply connector can break down ICs. Take protective measures against the breakdown due to the reverse connection, such as mounting an external diode between the power supply and the IC's power supply terminal.

(4) Power supply line

Design PCB pattern to provide low impedance for the wiring between the power supply and the GND lines. In this regard, for the digital block power supply and the analog block power supply, even though these power supplies has the same level of potential, separate the power supply pattern for the digital block from that for the analog block, thus suppressing the diffraction of digital noises to the analog block power supply resulting from impedance common to the wiring patterns. For the GND line, give consideration to design the patterns in a similar manner.

Furthermore, for all power supply terminals to ICs, mount a capacitor between the power supply and the GND terminal. At the same time, in order to use an electrolytic capacitor, thoroughly check to be sure the characteristics of the capacitor to be used present no problem including the occurrence of capacity dropout at a low temperature, thus determining the constant.

(5) GND voltage

Make setting of the potential of the GND terminal so that it will be maintained at the minimum in any operating state. Furthermore, check to be sure no terminals are at a potential lower than the GND voltage including an actual electric transient.

(6) Short circuit between terminals and erroneous mounting

In order to mount ICs on a set PCB, pay thorough attention to the direction and offset of the ICs. Erroneous mounting can break down the ICs. Furthermore, if a short circuit occurs due to foreign matters entering between terminals or between the terminal and the power supply or the GND terminal, the ICs can break down.

(7) Operation in strong electromagnetic field

Be noted that using ICs in the strong electromagnetic field can malfunction them.

(8) Inspection with set PCB

On the inspection with the set PCB, if a capacitor is connected to a low-impedance IC terminal, the IC can suffer stress. Therefore, be sure to discharge from the set PCB by each process. Furthermore, in order to mount or dismount the set PCB to/from the jig for the inspection process, be sure to turn OFF the power supply and then mount the set PCB to the jig. After the completion of the inspection, be sure to turn OFF the power supply and then dismount it from the jig. In addition, for protection against static electricity, establish a ground for the assembly process and pay thorough attention to the transportation and the storage of the set PCB.

(9) Input terminals

In terms of the construction of IC, parasitic elements are inevitably formed in relation to potential. The operation of the parasitic element can cause interference with circuit operation, thus resulting in a malfunction and then breakdown of the input terminal. Therefore, pay thorough attention not to handle the input terminals, such as to apply to the input terminals a voltage lower than the GND respectively, so that any parasitic element will operate. Furthermore, do not apply a voltage to the input terminals when no power supply voltage is applied to the IC. In addition, even if the power supply voltage is applied, apply to the input terminals a voltage lower than the power supply voltage or within the guaranteed value of electrical characteristics.

(10) Ground wiring pattern

If small-signal GND and large-current GND are provided, It will be recommended to separate the large-current GND pattern from the small-signal GND pattern and establish a single ground at the reference point of the set PCB so that resistance to the wiring pattern and voltage fluctuations due to a large current will cause no fluctuations in voltages of the small-signal GND. Pay attention not to cause fluctuations in the GND wiring pattern of external parts as well.

(11) External capacitor

In order to use a ceramic capacitor as the external capacitor, determine the constant with consideration given to a degradation in the nominal capacitance due to DC bias and changes in the capacitance due to temperature, etc.

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